

 <b>Material Composition Declaration</b> © Copyright 2005, IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
1752-21.1		IPC Web Site for Information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>			Form Type * Distribute		Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information			
<b>Supplier Information</b>										
Company name* <b>onsemi</b>			Company unique ID		Unique ID Authority			Response Date* <b>2025-07-07</b>		
Contact Name <b>Product-Env-Stewards</b>			Title - Contact Product Enviro Compliance		Phone - Contact* <b>NA</b>			Email - Contact* <b>Product-Env-Stewards@onsemi.com</b>		
Authorized Representative* <b>Product-Env-Stewards</b>			Title - Representative Product Enviro Compliance		Phone - Representative* <b>NA</b>			Email - Representative* <b>Product-Env-Stewards@onsemi.com</b>		
	Requester Item Number	Mfr Item Number	Mfr Item Name		Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
		ASX350AT3C00XPE A0-DR	VGA 1/5 SOC		2025-07-07		MY5	106.1	mg	Each
<b>Manufacturing Process Information</b>										
	Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature		Max Time at Peak Temperature		Number of Reflow Cycles	
	<b>SnAgCu</b>	<b>CU Alloy</b>	<b>3</b>		<b>260</b> C		<b>30</b> seconds		<b>3</b>	
Comments										
<b>ATTENTION: MSL 3 Rated item requires Bake and Dry Pack (after electrical test)</b>										
<b>For more information regarding material composition please refer to page 3</b>										

RoHS Material Composition Declaration		Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).		
<p>Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a “RoHS restricted substance”) in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.</p>			
RoHS Declaration *	1 - Item(s) does not contain RoHS restricted substances per the definition above		Supplier Acceptance * Accepted
<b>Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.</b>			
Exemption List Version	EL-2011/534/EU		
Declaration Signature			
<b>Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.</b>			
Supplier Digital Signature	Rastislav Drska		

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	23.9	mg		Misc.	proprietary data		0.0908	mg
			Supplier	Silicon (Si)	7440-21-3		23.5726	mg
			Supplier	Aluminum (Al)	7429-90-5		0.2366	mg
Die Attach	2.2	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.825	mg
			Supplier	Ethylene Glycol	107-21-1		0.022	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.066	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.462	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.825	mg
Imaging Lens	29.3	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.465	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.465	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		1.465	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.465	mg
			B	Antimony Trioxide (Sb2O3)	1309-64-4		0.1465	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.465	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.465	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		20.3635	mg
Lid Attach	1.52	mg	Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.684	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.304	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.19	mg
			Supplier	Acrylate Oligomer	Proprietary Data		0.0076	mg
			Supplier	Curative	Proprietary Data		0.0304	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.304	mg
Mold Compound-Black	8.1	mg		Phenolic Resin	proprietary data		1.215	mg
			Supplier	Oxirane	39817-09-9		1.215	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		0.243	mg
			Supplier	Carbon Black (C)	1333-86-4		0.081	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.184	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.162	mg
Solder Ball	21.73	mg	Supplier	Silver (Ag)	7440-22-4		0.6519	mg
			Supplier	Tin (Sn)	7440-31-5		20.9694	mg
			Supplier	Copper (Cu)	7440-50-8		0.1086	mg

Substrate and Solder Mask	19.1	mg	Supplier	Bis(3-ethyl-5-methyl-4-maleimidophenyl)methane	105391-33-1		0.2139	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		2.4754	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0287	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		0.445	mg
			Supplier	Cyanic acid (1-methylethylidene)di-4,1-phenylene ester homopolymer	25722-66-1		0.2139	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.1108	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0019	mg
			Supplier	Acetophenone Derivative	Proprietary Data		0.6666	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1108	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8		0.1108	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		2.292	mg
			B	Nickel (Ni)	7440-02-0		0.2693	mg
			Supplier	Gold (Au)	7440-57-5		0.0096	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5		1.3351	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.2139	mg
			Supplier	Copper (Cu)	7440-50-8		7.1549	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		3.4475	mg
Wire Bond - Au	0.25	mg	Supplier	Gold (Au)	7440-57-5		0.25	mg